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**Test method of positive photoresist for manufacturing of flat
panel display array**

平板显示阵列用正性光阻材料测试方法

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Table of Contents

Preface	III
1 Scope	1
2 Normative references	1
3 Terms and Definitions	1
4 Test Conditions	2
4.1 Environmental conditions	2
4.2 Reagents and Materials	2
4.3 Other Supporting Facilities	2
5 Test Item	2
5.1 Film Moire	2
5.2 Exposure	4
5.3 Exposure test to observe the integrity of the pattern	6
5.4 Critical Dimension (CD)	6
5.5 Residual film rate	7
5.6 Solid content	8
5.7 Liquid Particle Counting	9
5.8 Viscosity	10
5.9 Relative density	11
5.10 Water mass fraction	11
5.11 Metal impurity content	11
6 Test report	13

Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

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Positive photoresist materials for flat panel display arrays Test Methods

1 Scope

This document describes the test methods for positive photoresist materials used in flat panel display arrays.

This document is applicable to the performance testing of positive photoresist materials used in the manufacture of display arrays such as liquid crystal display devices and organic light-emitting display devices.

2 Normative references

GB/T 23942

GB/T 25915.1

GB/T 33087

GB/T 37403

GB/T 39486

3 Terms and definitions

The following terms and definitions apply to this document.

3.1 Exposure energy

The dose of light energy or other radiation energy absorbed per unit area of photoresist material.

Note. It is used to measure the sensitivity of photoresist materials to exposure. In optical exposure, under given exposure light intensity conditions, the sensitivity is usually adjusted by the exposure time. Exposure.

3.2 Substrate

Substrate material for photoresist coating.

Note. In this document, the substrate wafer may be a single crystal silicon wafer, an epitaxial silicon wafer, or a glass wafer for a flat panel display, etc.

3.3 Softbake/prebake

After the photoresist material passes through the coating process, the solvent in the photoresist film is evaporated through an oven or hot plate to form the adhesive required for the exposure process. Membrane process.

3.4 Hardbake

The photoresist material is baked in an oven or hot plate after being coated, pre-baked, exposed and developed.

Note. The solvent in the photoresist film is further evaporated so that it can be used in subsequent processes.

3.5 coating film mura

The uneven thickness or density of the photoresist material, the presence of foreign matter in the photoresist material, the unstable coating process, etc. may cause the film surface to form